



BGA Snap-on Heatsinks

EMULATION TECHNOLOGY, INC.

World Leader in Adapters, Clips, and Test Accessories



Standard BGA product provided as:

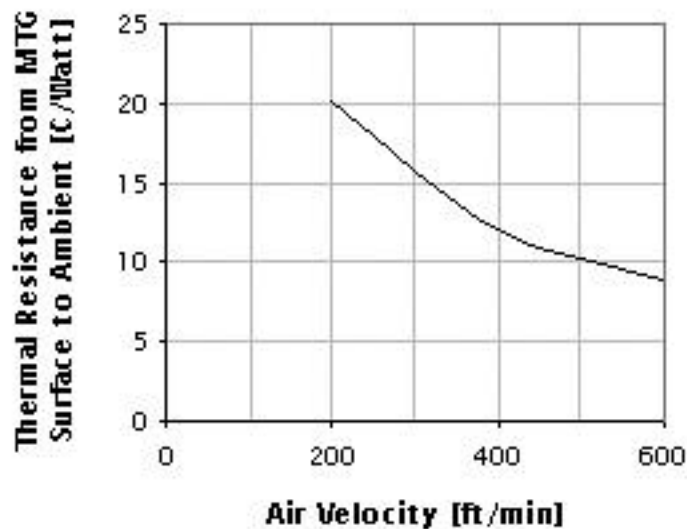
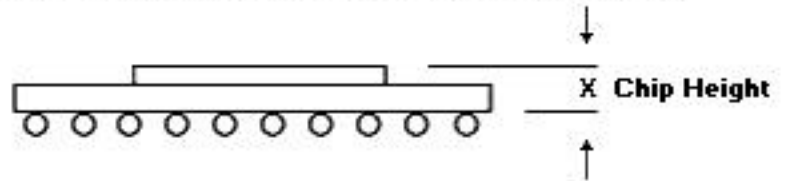
- Black anodized
- Pre-assembled as shown
- Customs available upon request

Other BGA products available:

- Rework Stencils
- Reballing Preforms
- Sockets
- Ultra-mini Pogo Pins

ET Part Number	Part Marking	Chip Pkg. Size (sq)	Heatsink Height	Fits Chip Height [x]
H-2303-03-9017-05-A	HS2134DCAB	23 mm	0.3 in (7.62 mm)	2.88 (+/- 0.16) mm
H-2303-04-9017-05-A	HS2099DCAB	23 mm	0.3 in (7.62 mm)	2.38 (+/- 0.26) mm

* Max dimensions include allowance for .005" thick thermal pad



EMULATION TECHNOLOGY, INC.
 2344 WALSH AVE.
 BLDG. F
 SANTA CLARA, CA 95051
 1-800-ADAPTER (232-7837)
www.1800ADAPTER.com

— HS2134DCAB - - - HS2099DCAB